Onsemi

Dual Bias Resistor Transistors **NPN and PNP Silicon Surface Mount**

Transistors with Monolithic Bias Resistor Network EMD4DXV6

The BRT (Bias Resistor Transistor) contains a single transistor with a monolithic bias network consisting of two resistors; a series base resistor and a base-emitter resistor. These digital transistors are designed to replace a single device and its external resistor bias network. The BRT eliminates these individual components by integrating them into a single device. In the EMD4DXV6T1 series, two complementary BRT devices are housed in the SOT-563 package which is ideal for low power surface mount applications where board space is at a premium.

Features

- Simplifies Circuit Design
- Reduces Board Space
- Reduces Component Count
- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These are Pb-Free Devices

MAXIMUM RATINGS (T _A = 25° C unless otherwise noted, common for Q ₁
and Q ₂ , – minus sign for Q ₁ (PNP) omitted)

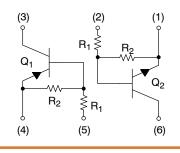
Rating	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	50	Vdc
Collector-Emitter Voltage	V _{CEO}	50	Vdc
Collector Current	Ι _C	100	mAdc

THERMAL CHARACTERISTICS

Characteristic (One Junction Heated)	Symbol	Мах	Unit
Total Device Dissipation $T_A = 25^{\circ}C$ (Note 1) Derate above 25^{C} (Note 1)	P _D	357 2.9	mW mW/°C
Thermal Resistance, Junction-to-Ambient (Note 1)	$R_{\theta JA}$	350	°C/W
Total Device Dissipation T _A = 25°C (Note 1) Derate above 25°C	P _D	500 4.0	mW mW/°C
Thermal Resistance, Junction-to-Ambient (Note 1)	$R_{\theta JA}$	250	°C/W
Junction and Storage Temperature	T _J , T _{stg}	-55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. FR-4 board with minimum mounting pad.





MARKING DIAGRAM



U7 = Specific Device Code M = Date Code = Pb–Free Package (Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping [†]
EMD4DXV6T1G	SOT–563 (Pb–Free)	4000 / Tape & Reel
EMD4DXV6T5G	SOT-563 (Pb-Free)	8000 / Tape & Reel
NSVEMD4DXV6T5G	SOT-563 (Pb-Free)	8000 / Tape & Reel
NSVEMD4DXV6T1G	SOT-563 (Pb-Free)	4000 / Tape & Reel

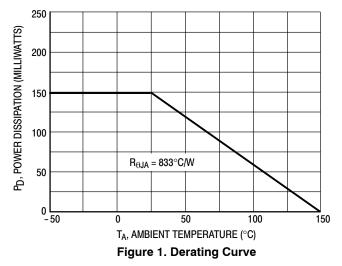
+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

EMD4DXV6

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted)

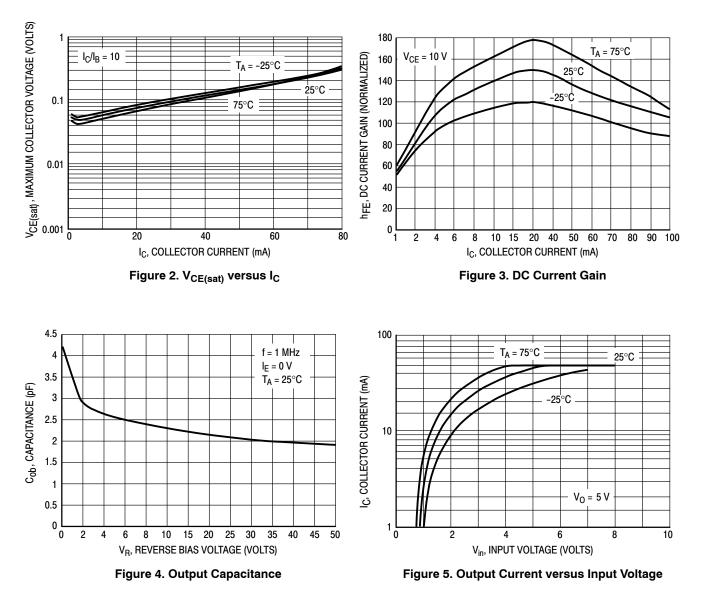
Characteristic	Symbol	Min	Тур	Max	Unit
Q1 TRANSISTOR: PNP	•	•			
OFF CHARACTERISTICS					
Collector-Base Cutoff Current (V _{CB} = 50 V, I_E = 0)	I _{CBO}	-	-	100	nAdc
Collector-Emitter Cutoff Current ($V_{CB} = 50 \text{ V}, I_B = 0$)	I _{CEO}	-	-	500	nAdc
Emitter-Base Cutoff Current (V_{EB} = 6.0, I_{C} = 5.0 mA)	I _{EBO}	-	-	0.2	mAdc
ON CHARACTERISTICS					
Collector-Base Breakdown Voltage (I _C = 10 μ A, I _E = 0)	V _{(BR)CBO}	50	-	-	Vdc
Collector-Emitter Breakdown Voltage ($I_C = 2.0 \text{ mA}, I_B = 0$)	V _{(BR)CEO}	50	-	-	Vdc
DC Current Gain (V_{CE} = 10 V, I_{C} = 5.0 mA)	h _{FE}	80	140	-	
Collector-Emitter Saturation Voltage (I_C = 10 mA, I_B = 0.3 mA)	V _{CE(SAT)}	-	-	0.25	Vdc
Output Voltage (on) (V_{CC} = 5.0 V, V_B = 2.5 V, R_L = 1.0 k\Omega)	V _{OL}	-	-	0.2	Vdc
Output Voltage (off) (V_{CC} = 5.0 V, V_B = 0.5 V, R_L = 1.0 k\Omega)	V _{OH}	4.9	-	-	Vdc
Input Resistor	R1	7.0	10	13	kΩ
Resistor Ratio	R1/R2	0.17	0.21	0.25	
Q2 TRANSISTOR: NPN					
OFF CHARACTERISTICS					
Collector-Base Cutoff Current (V _{CB} = 50 V, I_E = 0)	I _{CBO}	-	-	100	nAdc
Collector-Emitter Cutoff Current (V_{CB} = 50 V, I_B = 0)	I _{CEO}	-	-	500	nAdc
Emitter-Base Cutoff Current (V_{EB} = 6.0, I_{C} = 0 mA)	I _{EBO}	-	-	0.1	mAdc
ON CHARACTERISTICS					
Collector-Base Breakdown Voltage (I _C = 10 μ A, I _E = 0)	V _{(BR)CBO}	50	-	-	Vdc
Collector-Emitter Breakdown Voltage ($I_C = 2.0 \text{ mA}, I_B = 0$)	V _{(BR)CEO}	50	-	-	Vdc
DC Current Gain (V_{CE} = 10 V, I_{C} = 5.0 mA)	h _{FE}	80	140	-	
Collector-Emitter Saturation Voltage (I_C = 10 mA, I_B = 0.3 mA)	V _{CE(SAT)}	-	-	0.25	Vdc
Output Voltage (on) (V_{CC} = 5.0 V, V_B = 3.5 V, R_L = 1.0 k Ω)	V _{OL}	-	-	0.2	Vdc
Output Voltage (off) (V_{CC} = 5.0 V, V_B = 0.5 V, R_L = 1.0 k Ω)	V _{OH}	4.9	-	-	Vdc
Input Resistor	R1	32.9	47	61.1	kΩ
Resistor Ratio	R1/R2	0.8	1.0	1.2	

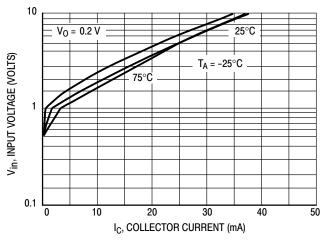
Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

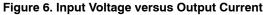


EMD4DXV6

TYPICAL ELECTRICAL CHARACTERISTICS — EMD4DXV6 PNP TRANSISTOR







EMD4DXV6

TYPICAL ELECTRICAL CHARACTERISTICS — EMD4DXV6 NPN TRANSISTOR

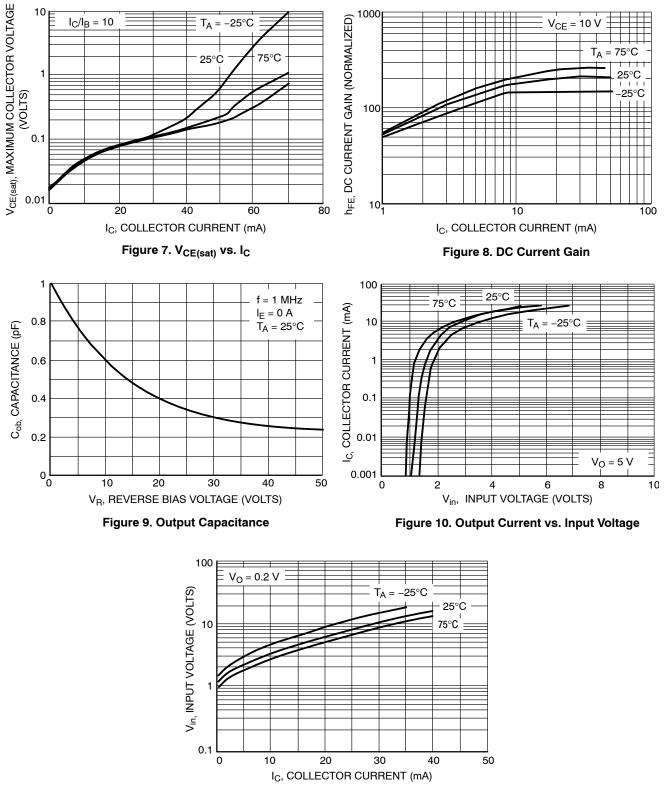


Figure 11. Input Voltage vs. Output Current

6Х

(

MILLIMETERS

NDM.

0.55

0.22

0.13

1.60

1.20

0.50 BSC

0.20

1.60

MAX.

0.60

0.27

0.18

1.70

1.30

0.30

1.70

SIDE VIEW

MIN.

0.50

0.17

0.08

1.50

1.10

0.10

1.50

DIM

Α

b

С

D E

e L

 H_E



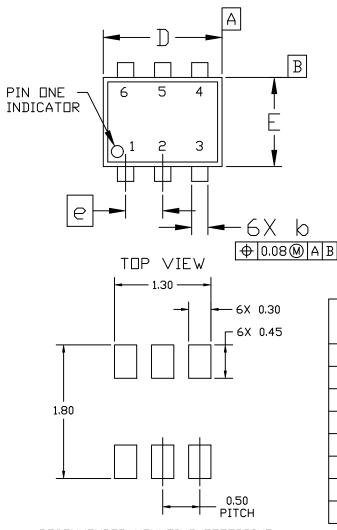


SOT-563, 6 LEAD CASE 463A ISSUE H

DATE 26 JAN 2021

ALE 4:1

- NDTES: 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
- 1. DIMENSIONING AND TOLERANCING PER A 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS DF BASE MATERIAL.



RECOMMENDED MOUNTING FOOTPRINT* * For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SDLDERRM/D.

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STYLE 1:	STYLE 2:	STYLE 3:
PIN 1. EMITTER 1	PIN 1. EMITTER 1	PIN 1. CATHIDE 1
2. BASE 1	2. EMITTER 2	2. CATHIDE 1
3. COLLECTOR 2	3. BASE 2	3. ANUDE/ANUDE 2
4. EMITTER 2	4. COLLECTOR 2	4. CATHIDE 2
5. BASE 2	5. BASE 1	5. CATHIDE 2
6. COLLECTOR 1	6. COLLECTOR 1	6. ANUDE/ANUDE 1
STYLE 4:	STYLE 5:	STYLE 6:
PIN 1. COLLECTOR	PIN 1. CATHEDE	PIN 1. CATHODE
2. COLLECTOR	2. CATHEDE	2. ANODE
3. BASE	3. ANEDE	3. CATHODE
4. EMITTER	4. ANEDE	4. CATHODE
5. COLLECTOR	5. CATHEDE	5. CATHODE
6. COLLECTOR	6. CATHEDE	6. CATHODE
STYLE 7:	STYLE 8:	STYLE 9:
PIN 1. CATHODE	PIN 1. DRAIN	PIN 1. SDURCE 1
2. ANODE	2. DRAIN	2. GATE 1
3. CATHODE	3. GATE	3. DRAIN 2
4. CATHODE	4. SDURCE	4. SDURCE 2
5. ANODE	5. DRAIN	5. GATE 2
6. CATHODE	6. DRAIN	6. DRAIN 1
STYLE 10: PIN 1. CATHIDE 1 2. N/C 3. CATHIDE 2 4. ANIDE 2 5. N/C 6. ANIDE 1	STYLE 11: PIN 1. EMITTER 2 2. BASE 2 3. COLLECTOR 1 4. EMITTER 1 5. BASE 1 6. COLLECTOR 2	

6. COLLECTOR 2

DATE 26 JAN 2021

GENERIC **MARKING DIAGRAM***



XX = Specific Device Code

M = Month Code

. = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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